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### Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

### Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

#### Details

Product Status	Obsolete
Core Processor	MIPS32
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	300MHz
Co-Processors/DSP	-
RAM Controllers	DDR
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	256-LBGA
Supplier Device Package	256-CABGA (17x17)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/79rc32h434-300bc">https://www.e-xfl.com/product-detail/renesas-electronics-america/79rc32h434-300bc</a>

#### ♦ Memory and Peripheral Device Controller

- Provides “glueless” interface to standard SRAM, Flash, ROM, dual-port memory, and peripheral devices
- Demultiplexed address and data buses: 8-bit data bus, 26-bit address bus, 4 chip selects, control for external data bus buffers
- Automatic byte gathering and scattering
- Flexible protocol configuration parameters: programmable number of wait states (0 to 63), programmable postread/post-write delay (0 to 31), supports external wait state generation, supports Intel and Motorola style peripherals
- Write protect capability per chip select
- Programmable bus transaction timer generates warm reset when counter expires
- Supports up to 64 MB of memory per chip select

#### ♦ DMA Controller

- 6 DMA channels: two channels for PCI (PCI to Memory and Memory to PCI), two channels for the Ethernet interface, and two channels for memory to memory DMA operations
- Provides flexible descriptor based operation
- Supports unaligned transfers (i.e., source or destination address may be on any byte boundary) with arbitrary byte length

#### ♦ Universal Asynchronous Receiver Transmitter (UART)

- Compatible with the 16550 and 16450 UARTs
- 16-byte transmit and receive buffers
- Programmable baud rate generator derived from the system clock
- Fully programmable serial characteristics:
  - 5, 6, 7, or 8 bit characters
  - Even, odd or no parity bit generation and detection
  - 1, 1-1/2 or 2 stop bit generation
- Line break generation and detection
- False start bit detection
- Internal loopback mode

#### ♦ I<sup>2</sup>C-Bus

- Supports standard 100 Kbps mode as well as 400 Kbps fast mode
- Supports 7-bit and 10-bit addressing
- Supports four modes: master transmitter, master receiver, slave transmitter, slave receiver

#### ♦ Additional General Purpose Peripherals

- Interrupt controller
- System integrity functions
- General purpose I/O controller
- Serial peripheral interface (SPI)

#### ♦ Counter/Timers

- Three general purpose 32-bit counter timers
- Timers may be cascaded
- Selectable counter/timer clock source

#### ♦ JTAG Interface

- Compatible with IEEE Std. 1149.1 - 1990

#### CPU Execution Core

The 32-bit CPU core is 100% compatible with the MIPS32 instruction set architecture (ISA). Specifically, this device features the 4Kc CPU core developed by MIPS Technologies Inc. ([www.mips.com](http://www.mips.com)). This core issues a single instruction per cycle, includes a five stage pipeline and is optimized for applications that require integer arithmetic.

The CPU core includes 8 KB instruction and 8 KB data caches. Both caches are 4-way set associative and can be locked on a per line basis, which allows the programmer control over this precious on-chip memory resource. The core also features a memory management unit (MMU). The CPU core also incorporates an enhanced joint test access group (EJTAG) interface that is used to interface to in-circuit emulator tools, providing access to internal registers and enabling the part to be controlled externally, simplifying the system debug process.

The use of this core allows IDT's customers to leverage the broad range of software and development tools available for the MIPS architecture, including operating systems, compilers, and in-circuit emulators.

#### PCI Interface

The PCI interface on the RC32434 is compatible with version 2.2 of the PCI specification. An on-chip arbiter supports up to six external bus masters, supporting both fixed priority and rotating priority arbitration schemes. The part can support both satellite and host PCI configurations, enabling the RC32434 to act as a slave controller for a PCI add-in card application or as the primary PCI controller in the system. The PCI interface can be operated synchronously or asynchronously to the other I/O interfaces on the RC32434 device.

#### Ethernet Interface

The RC32434 has one Ethernet Channel supporting 10Mbps and 100Mbps speeds to provide a standard media independent interface (MII or RMII), allowing a wide range of external devices to be connected efficiently.

#### Double Data Rate Memory Controller

The RC32434 incorporates a high performance double data rate (DDR) memory controller which supports x16 memory configurations up to 256MB. This module provides all of the signals required to interface to discrete memory devices, including a chip select, differential clocking outputs and data strobes.

#### Memory and I/O Controller

The RC32434 uses a dedicated local memory/I/O controller including a de-multiplexed 8-bit data and 26-bit address bus. It includes all of the signals required to interface directly to a maximum of four Intel or Motorola-style external peripherals.

## DMA Controller

The DMA controller consists of 6 independent DMA channels, all of which operate in exactly the same manner. The DMA controller off-loads the CPU core from moving data among the on-chip interfaces, external peripherals, and memory. The controller supports scatter/gather DMA with no alignment restrictions, making it appropriate for communications and graphics systems.

## UART Interface

The RC32434 contains a serial channel (UART) that is compatible with the industry standard 16550 UART.

## I<sup>2</sup>C Interface

The standard I2C interface allows the RC32434 to connect to a number of standard external peripherals for a more complete system solution. The RC32434 supports both master and slave operations.

## General Purpose I/O Controller

The RC32434 has 14 general purpose input/output pins. Each pin may be used as an active high or active low level interrupt or non-maskable interrupt input, and each signal may be used as a bit input or output port.

## System Integrity Functions

The RC32434 contains a programmable watchdog timer that generates a non-maskable interrupt (NMI) when the counter expires and also contains an address space monitor that reports errors in response to accesses to undecoded address regions.

## Thermal Considerations

The RC32434 is guaranteed in an ambient temperature range of 0° to +70° C for commercial temperature devices and - 40° to +85° for industrial temperature devices.

## Revision History

**November 3, 2003:** Initial publication. Preliminary Information.

**December 15, 2003:** Final version. In Table 7, changed maximum value for Tskew in 266MHz category and changed values for Tdo in all speed grades for signals DDRADDR, etc. In Table 8, changed minimum values in all speed grades for all Tdo signals and for Tsu and Tzd in MDATA[7:0]. In Table 16, added reference to Power Considerations document. In Table 17, added 2 rows under PCI and Notes 1 and 2.

**January 5, 2004:** In Table 19, Pin F6 was changed from Vcc I/O to Vss. In Table 23, pin F6 was deleted from the Vcc I/O row and added to the Vss row.

**January 27, 2004:** In Table 3, revised description for MADDR[3:0] and changed 4096 cycles to 4000 for MADDR[7]. (Note: MADDR was incorrectly labeled as MDATA in previous data sheet.)

**March 29, 2004:** Added Standby mode to Table 16, Power Consumption.

**April 19, 2004:** Added the I<sup>2</sup>C feature. In Table 20, pin L1 becomes SDA and pin L2 becomes SCL.

**May 25, 2004:** In Table 9, signals MIIRXCLK and MIITXCLK, the Min and Max values for Thigh/Tlow\_9c were changed to 140 and 260 respectively and the Min and Max values for Thigh/Tlow\_9d were changed to 14.0 and 26.0 respectively.

**December 8, 2005:** In Table 18, corrected error for Capacitance Max value from 8.0 to 10.5.

**January 19, 2006:** Removed all references to NVRAM.

Signal	Type	Name/Description
PCILOCKN	I/O	<b>PCI Lock.</b> This signal is asserted by an external bus master to indicate that an exclusive operation is occurring.
PCIPAR	I/O	<b>PCI Parity.</b> Even parity of the PCIAD[31:0] bus. Driven by the bus master during address and write Data phases. Driven by the bus target during the read data phase.
PCIPERRN	I/O	<b>PCI Parity Error.</b> If a parity error is detected, this signal is asserted by the receiving bus agent 2 clocks after the data is received.
PCIREQN[3:0]	I/O	<b>PCI Bus Request.</b> <b>In PCI host mode with internal arbiter:</b> These signals are inputs whose assertion indicates to the internal RC32434 arbiter that an agent desires ownership of the PCI bus. <b>In PCI host mode with external arbiter:</b> PCIREQN[0]: asserted by the RC32434 to request ownership of the PCI bus. PCIREQN[3:1]: unused and driven high. <b>In PCI satellite mode:</b> PCIREQN[0]: this signal is asserted by the RC32434 to request use of the PCI bus. PCIREQN[1]: function changes to PCIIDSEL and is used as a chip select during configuration read and write transactions. PCIREQN[3:2]: unused and driven high.
PCIRSTN	I/O	<b>PCI Reset.</b> In host mode, this signal is asserted by the RC32434 to generate a PCI reset. In satellite mode, assertion of this signal initiates a warm reset.
PCISERRN	I/O	<b>PCI System Error.</b> This signal is driven by an agent to indicate an address parity error, data parity error during a special cycle command, or any other system error. Requires an external pull-up.
PCISTOPN	I/O	<b>PCI Stop.</b> Driven by the bus target to terminate the current bus transaction. For example, to indicate a retry.
PCITRDYN	I/O	<b>PCI Target Ready.</b> Driven by the bus target to indicate that the current data can complete.
<b>General Purpose Input/Output</b>		
GPIO[0]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0SOUT Alternate function: UART channel 0 serial output.
GPIO[1]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0SINP Alternate function: UART channel 0 serial input.
GPIO[2]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0RTSN Alternate function: UART channel 0 request to send.
GPIO[3]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: U0CTSN Alternate function: UART channel 0 clear to send.

Table 1 Pin Description (Part 3 of 6)

Signal	Type	Name/Description
GPIO[4]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[22] Alternate function: Memory and peripheral bus address.
GPIO[5]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[23] Alternate function: Memory and peripheral bus address.
GPIO[6]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[24] Alternate function: Memory and peripheral bus address. The value of this pin may be used as a counter timer clock input (see Counter Timer Clock Select Register in Chapter 14, Counter/Timers, of the RC32434 User Manual).
GPIO[7]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: MADDR[25] Alternate function: Memory and peripheral bus address. The value of this pin may be used as a counter timer clock input (see Counter Timer Clock Select Register in Chapter 14, Counter/Timers, of the RC32434 User Manual).
GPIO[8]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: CPU Alternate function: CPU or DMA debug output pin.
GPIO[9]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIREQN[4] Alternate function: PCI Request 4.
GPIO[10]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIGNTN[4] Alternate function: PCI Grant 4.
GPIO[11]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIREQN[5] Alternate function: PCI Request 5.
GPIO[12]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIGNTN[5] Alternate function: PCI Grant 5.
GPIO[13]	I/O	<b>General Purpose I/O.</b> This pin can be configured as a general purpose I/O pin. Alternate function pin name: PCIMUINTN Alternate function: PCI Messaging unit interrupt output.
<b>SPI Interface</b>		
SCK	I/O	<b>Serial Clock.</b> This signal is used as the serial clock output. This pin may be used as a bit input/output port.

Table 1 Pin Description (Part 4 of 6)

Signal	Type	Name/Description
SDI	I/O	<b>Serial Data Input.</b> This signal is used to shift in serial data. This pin may be used as a bit input/output port.
SDO	I/O	<b>Serial Data Output.</b> This signal is used shift out serial data.
<b>I<sup>2</sup>C Bus Interface</b>		
SCL	I/O	<b>I<sup>2</sup>C Clock.</b> I <sup>2</sup> C-bus clock.
SDA	I/O	<b>I<sup>2</sup>C Data Bus.</b> I <sup>2</sup> C-bus data bus.
<b>Ethernet Interfaces</b>		
MIICL	I	<b>Ethernet MII Collision Detected.</b> This signal is asserted by the ethernet PHY when a collision is detected.
MIICRS	I	<b>Ethernet MII Carrier Sense.</b> This signal is asserted by the ethernet PHY when either the transmit or receive medium is not idle.
MIIRXCLK	I	<b>Ethernet MII Receive Clock.</b> This clock is a continuous clock that provides a timing reference for the reception of data. This pin also functions as the RMII REF_CLK input.
MIIRXD[3:0]	I	<b>Ethernet MII Receive Data.</b> This nibble wide data bus contains the data received by the ethernet PHY. This pin also functions as the RMII RXD[1:0] input.
MIIRXDV	I	<b>Ethernet MII Receive Data Valid.</b> The assertion of this signal indicates that valid receive data is in the MII receive data bus. This pin also functions as the RMII CRS_DV input.
MIIRXER	I	<b>Ethernet MII Receive Error.</b> The assertion of this signal indicates that an error was detected somewhere in the ethernet frame currently being sent in the MII receive data bus. This pin also functions as the RMII RX_ER input.
MIITXCLK	I	<b>Ethernet MII Transmit Clock.</b> This clock is a continuous clock that provides a timing reference for the transfer of transmit data.
MIITXD[3:0]	O	<b>Ethernet MII Transmit Data.</b> This nibble wide data bus contains the data to be transmitted. This pin also functions as the RMII TXD[1:0] output.
MIITXENP	O	<b>Ethernet MII Transmit Enable.</b> The assertion of this signal indicates that data is present on the MII for transmission. This pin also functions as the RMII TX_EN output.
MIITXER	O	<b>Ethernet MII Transmit Coding Error.</b> When this signal is asserted together with MIITXENP, the ethernet PHY will transmit symbols which are not valid data or delimiters.
MIIMDC	O	<b>MII Management Data Clock.</b> This signal is used as a timing reference for transmission of data on the management interface.
MIIMDIO	I/O	<b>MII Management Data.</b> This bidirectional signal is used to transfer data between the station management entity and the ethernet PHY.
<b>EJTAG / JTAG</b>		
JTAG_TMS	I	<b>JTAG Mode.</b> The value on this signal controls the test mode select of the boundary scan logic or JTAG Controller. When using the EJTAG debug interface, this pin should be left disconnected (since there is an internal pull-up) or driven high.

Table 1 Pin Description (Part 5 of 6)

Signal	Type	Name/Description
EJTAG_TMS	I	<b>EJTAG Mode.</b> The value on this signal controls the test mode select of the EJTAG Controller. When using the JTAG boundary scan, this pin should be left disconnected (since there is an internal pull-up) or driven high.
JTAG_TRST_N	I	<b>JTAG Reset.</b> This active low signal asynchronously resets the boundary scan logic, JTAG TAP Controller, and the EJTAG Debug TAP Controller. An external pull-up on the board is recommended to meet the JTAG specification in cases where the tester can access this signal. However, for systems running in functional mode, one of the following should occur: 1) actively drive this signal low with control logic 2) statically drive this signal low with an external pull-down on the board 3) clock JTAG_TCK while holding EJTAG_TMS and/or JTAG_TMS high.
JTAG_TCK	I	<b>JTAG Clock.</b> This is an input test clock used to clock the shifting of data into or out of the boundary scan logic, JTAG Controller, or the EJTAG Controller. JTAG_TCK is independent of the system and the processor clock with a nominal 50% duty cycle.
JTAG_TDO	O	<b>JTAG Data Output.</b> This is the serial data shifted out from the boundary scan logic, JTAG Controller, or the EJTAG Controller. When no data is being shifted out, this signal is tri-stated.
JTAG_TDI	I	<b>JTAG Data Input.</b> This is the serial data input to the boundary scan logic, JTAG Controller, or the EJTAG Controller.
<b>System</b>		
CLK	I	<b>Master Clock.</b> This is the master clock input. The processor frequency is a multiple of this clock frequency. This clock is used as the system clock for all memory and peripheral bus operations.
EXTBCV	I	<b>Load External Boot Configuration Vector.</b> When this pin is asserted (i.e., high) the boot configuration vector is loaded from an externally supplied value during a cold reset.
EXTCLK	O	<b>External Clock.</b> This clock is used for all memory and peripheral bus operations.
COLDRSTN	I	<b>Cold Reset.</b> The assertion of this signal initiates a cold reset. This causes the processor state to be initialized, boot configuration to be loaded, and the internal PLL to lock onto the master clock (CLK).
RSTN	I/O	<b>Reset.</b> The assertion of this bidirectional signal initiates a warm reset. This signal is asserted by the RC32434 during a warm reset.

Table 1 Pin Description (Part 6 of 6)

## Pin Characteristics

**Note:** Some input pads of the RC32434 do not contain internal pull-ups or pull-downs. Unused inputs should be tied off to appropriate levels. This is especially critical for unused control signal inputs (such as WAITACKN) which, if left floating, could adversely affect the RC32434's operation. Also, any input pin left floating can cause a slight increase in power consumption.

## AC Timing Definitions

Below are examples of the AC timing characteristics used throughout this document.

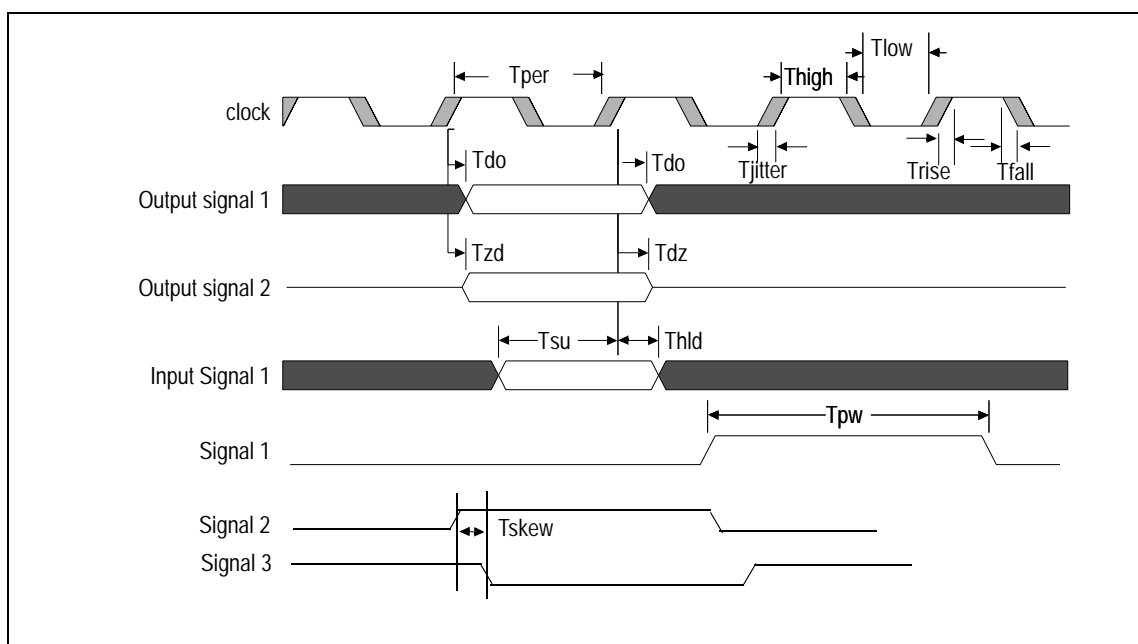


Figure 2 AC Timing Definitions Waveform

Symbol	Definition
Tper	Clock period.
Tlow	Clock low. Amount of time the clock is low in one clock period.
Thigh	Clock high. Amount of time the clock is high in one clock period.
Trise	Rise time. Low to high transition time.
Tfall	Fall time. High to low transition time.
Tjitter	Jitter. Amount of time the reference clock (or signal) edge can vary on either the rising or falling edges.
Tdo	Data out. Amount of time after the reference clock edge that the output will become valid. The minimum time represents the data output hold. The maximum time represents the earliest time the designer can use the data.
Tzd	Z state to data valid. Amount of time after the reference clock edge that the tri-stated output takes to become valid.
Tdz	Data valid to Z state. Amount of time after the reference clock edge that the valid output takes to become tri-stated.
Tsu	Input set-up. Amount of time before the reference clock edge that the input must be valid.
Thld	Input hold. Amount of time after the reference clock edge that the input must remain valid.
Tpw	Pulse width. Amount of time the input or output is active for asynchronous signals.
Tslew	Slew rate. The rise or fall rate for a signal to go from a high to low, or low to high.
X(clock)	Timing value. This notation represents a value of 'X' multiplied by the clock time period of the specified clock. Using 5(CLK) as an example: X = 5 and the oscillator clock (CLK) = 25MHz, then the timing value is 200.
Tskew	Skew. The amount of time two signal edges deviate from one another.

Table 4 AC Timing Definitions



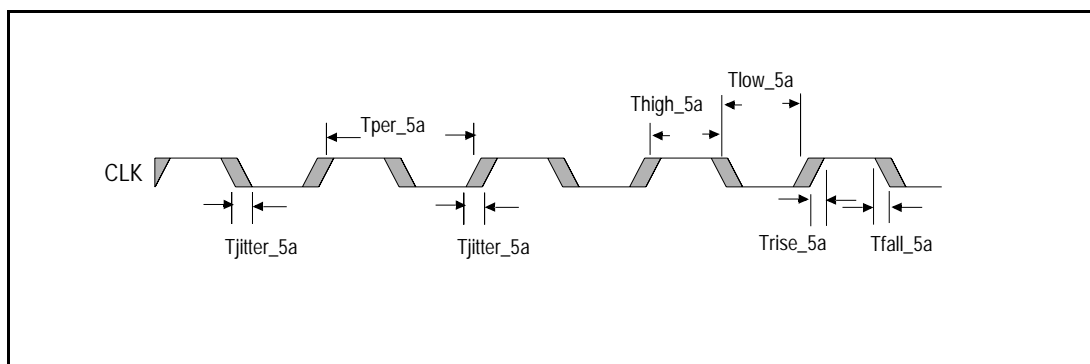
## System Clock Parameters

(Values based on systems running at recommended supply voltages and operating temperatures, as shown in Tables 15 and 16.)

Parameter	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Units	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max		
PCLK <sup>1</sup>	Frequency	none	200	266	200	300	200	350	200	400	MHz	See Figure 3.
	Tper		3.8	5.0	3.3	5.0	2.85	5.0	2.5	5.0	ns	
ICLK <sup>2,3,4</sup>	Frequency	none	100	133	100	150	100	175	100	200	MHz	
	Tper		7.5	10.0	6.7	10.0	5.7	10.0	5.0	10.0	ns	
CLK <sup>5</sup>	Frequency	none	25	125	25	125	25	125	25	125	MHz	
	Tper_5a		8.0	40.0	8.0	40.0	8.0	40.0	8.0	40.0	ns	
	Thigh_5a, Tlow_5a		40	60	40	60	40	60	40	60	% of Tper_5a	
	Trise_5a, Tfall_5a		—	3.0	—	3.0	—	3.0	—	3.0	ns	
	Tjitter_5a		—	0.1	—	0.1	—	0.1	—	0.1	ns	

**Table 5 Clock Parameters**

- <sup>1</sup> The CPU pipeline clock (PCLK) speed is selected during cold reset by the boot configuration vector (see Table 3). Refer to Chapter 3, Clocking and Initialization, in the RC32434 User Reference Manual for the allowable frequency ranges of CLK and PCLK.
- <sup>2</sup> ICLK is the internal IPBus clock. It is always equal to PCLK divided by 2. This clock cannot be sampled externally.
- <sup>3</sup> The ethernet clock (MIIXRXCLK and MIIXTXCLK) frequency must be equal to or less than 1/2 ICLK ( $MIIXRXCLK \text{ and } MIIXTXCLK \leq 1/2(ICLK)$ ).
- <sup>4</sup> PCICLK must be equal to or less than two times ICLK ( $PCICLK \leq 2(ICLK)$ ) with a maximum PCICLK of 66 MHz.
- <sup>5</sup> The input clock (CLK) is input from the external oscillator to the internal PLL.



**Figure 3 Clock Parameters Waveform**

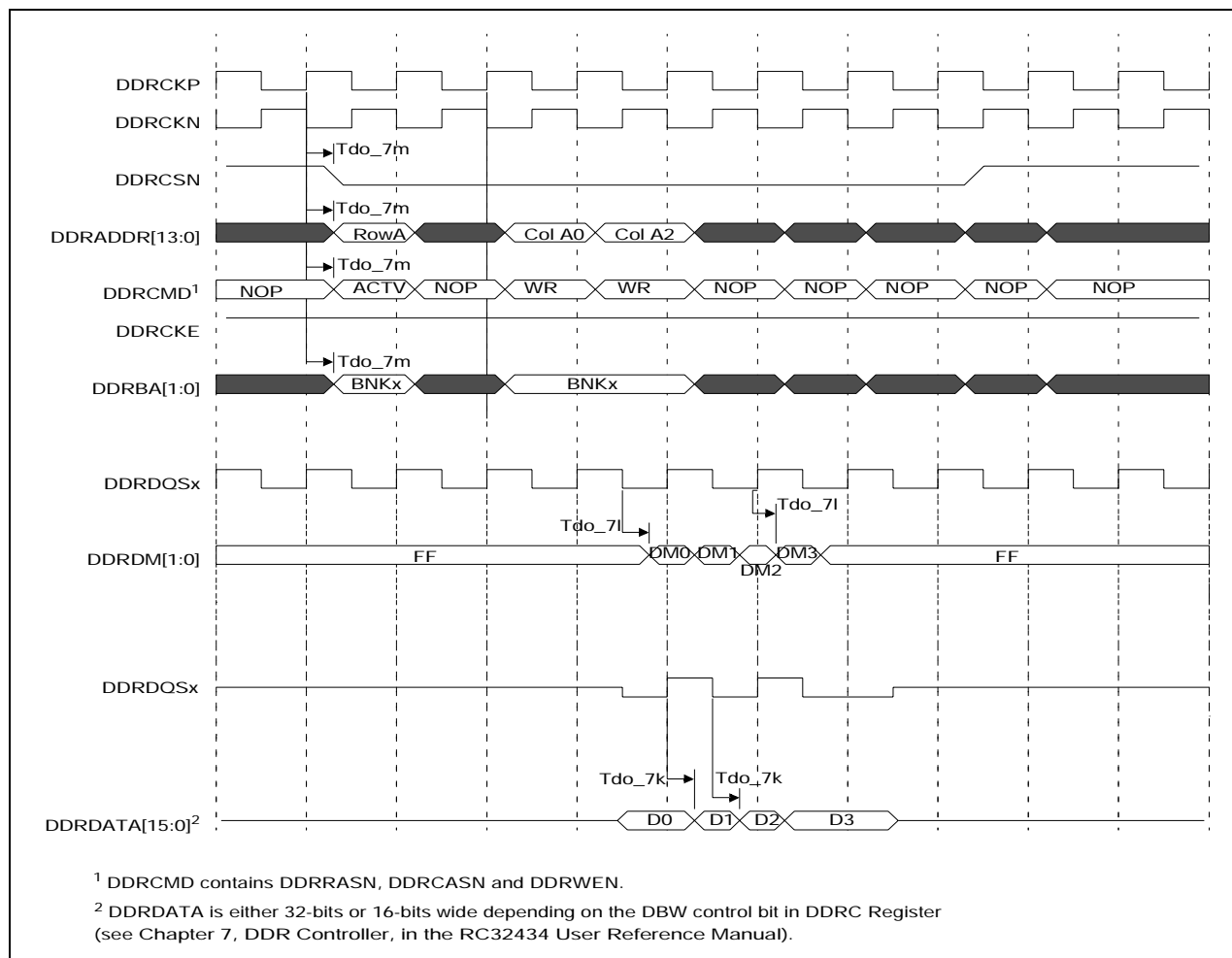


Figure 7 DDR SDRAM Timing Waveform — Write Access

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi-tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
Memory and Peripheral Bus <sup>1</sup>													See Figures 8 and 9.
MADDR[21:0]	Tdo_8a	EXTCLK rising	0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8a <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8a <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
MADDR[25:22]	Tdo_8b	EXTCLK rising	0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8b <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8b <sup>2</sup>		—	—	—	—	—	—	—	—	ns		

Table 8 Memory and Peripheral Bus AC Timing Characteristics (Part 1 of 2)

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi- tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
MDATA[7:0]	Tsu_8c	EXTCLK rising	6.0	—	6.0	—	6.0	—	6.0	—	ns		See Figures 8 and 9 (cont.).
	Thld_8c		0	—	0	—	0	—	0	—	ns		
	Tdo_8c		0.4	4.5	0.4	4.5	0.4	4.5	0.4	4.5	ns		
	Tdz_8c <sup>2</sup>		0	0.5	0	0.5	0	0.5	0	0.5	ns		
	Tzd_8c <sup>2</sup>		0.4	3.3	0.4	3.3	0.4	3.3	0.4	3.3	ns		
EXTCLK <sup>3</sup>	Tper_8d	none	7.5	—	6.66	—	6.66	—	6.66	—	ns		
BDIRN	Tdo_8e	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8e <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8e <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
BOEN	Tdo_8f	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8f <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8f <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
WAITACKN <sup>4</sup>	Tsu_8h	EXTCLK rising	6.5	—	6.5	—	6.5	—	6.5	—	ns		
	Thld_8h		0	—	0	—	0	—	0	—	ns		
	Tpw_8h <sup>2</sup>	none	2(EXTCLK)	—	2(EXTCLK)	—	2(EXTCLK)	—	2(EXTCLK)	—	ns		
CSN[3:0]	Tdo_8i	EXTCLK rising	0.4	4.0	0.4	4.0	0.4	4.0	0.4	4.0	ns		
	Tdz_8i <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8i <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
RWN	Tdo_8j	EXTCLK rising	0.4	3.8	0.4	3.8	0.4	3.8	0.4	3.8	ns		
	Tdz_8j <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8j <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
OEN	Tdo_8k	EXTCLK rising	0.4	4.0	0.4	4.0	0.4	4.0	0.4	4.0	ns		
	Tdz_8k <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8k <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
WEN	Tdo_8l	EXTCLK rising	0.4	3.7	0.4	3.7	0.4	3.7	0.4	3.7	ns		
	Tdz_8l <sup>2</sup>		—	—	—	—	—	—	—	—	ns		
	Tzd_8l <sup>2</sup>		—	—	—	—	—	—	—	—	ns		

Table 8 Memory and Peripheral Bus AC Timing Characteristics (Part 2 of 2)

<sup>1</sup>. The RC32434 provides bus turnaround cycles to prevent bus contention when going from read to write, write to read, and during external bus ownership. For example, there are no cycles where an external device and the RC32434 are both driving. See Chapter 6, Device Controller, in the RC32434 User Reference Manual.

<sup>2</sup>. The values for this symbol were determined by calculation, not by testing.

<sup>3</sup>. The frequency of EXTCLK is programmable. See the External Clock Divider (MDATA[5:4]) description in Table 3 of this data sheet.

<sup>4</sup>. WAITACKN must meet the setup and hold times if it is synchronous or the minimum pulse width if it is asynchronous.

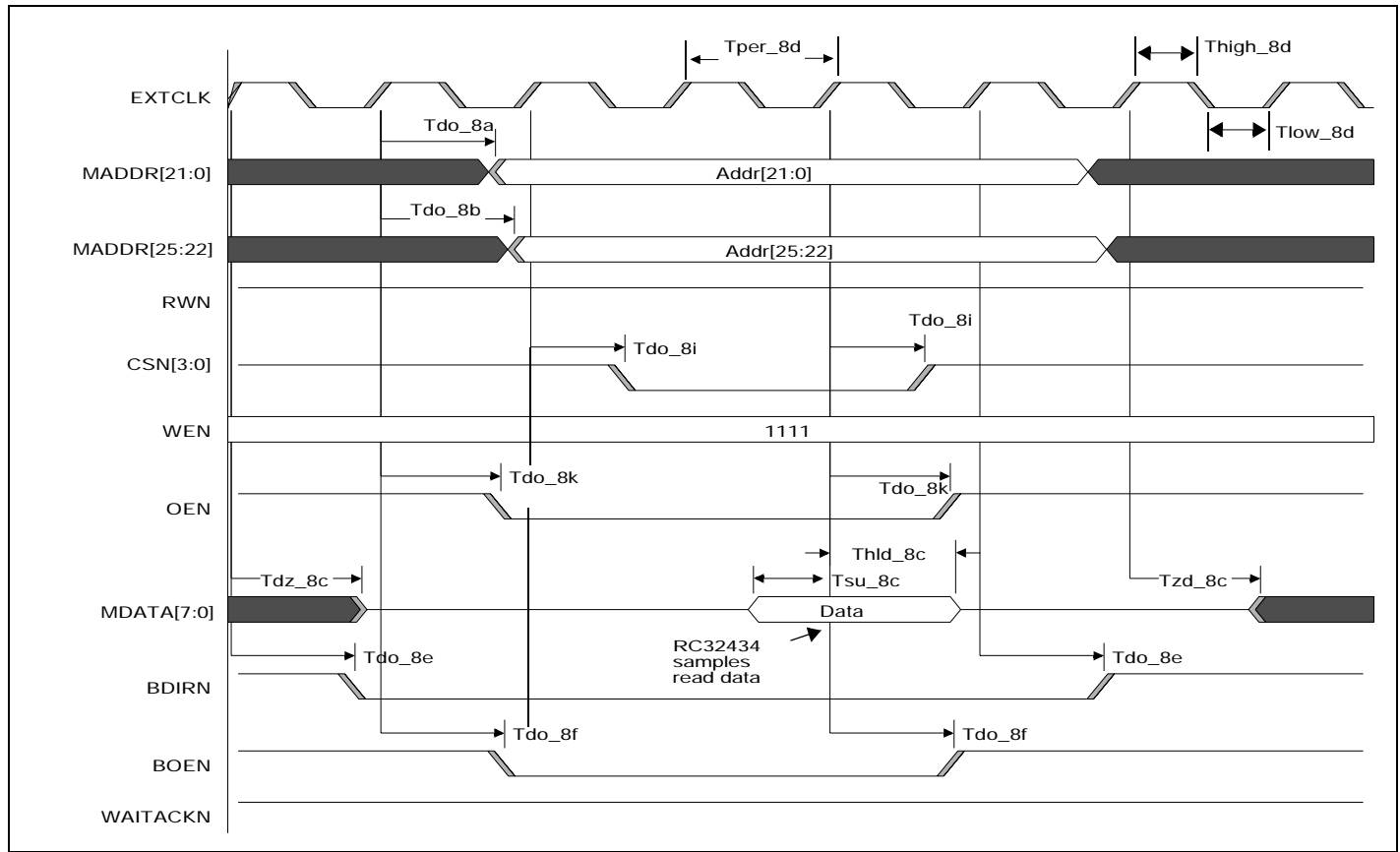


Figure 8 Memory and Peripheral Bus AC Timing Waveform — Read Access

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi- tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
Ethernet													
MIIMDC	Tper_9a	None	30.0	—	30.0	—	30.0	—	30.0	—	ns		See Figure 10.
	Thigh_9a, Tlow_9a		12.0	—	12.0	—	12.0	—	12.0	—	ns		
MIIMDIO	Tsu_9b	MIIMDC rising	10.0	—	10.0	—	10.0	—	10.0	—	ns		
	Thld_9b		0.0	—	0.0	—	0.0	—	0.0	—	ns		
	Tdo_9b <sup>1</sup>		10	300	10	300	10	300	10	300	ns		
Ethernet — MII Mode													
MIIRXCLK, MIITXCLK <sup>2</sup>	Tper_9c	None	399.96	400.4	399.96	400.4	399.96	400.4	399.96	400.4	ns	10 Mbps	See Figure 10.
	Thigh_9c, Tlow_9c		140	260	140	260	140	260	140	260	ns		
	Trise_9c, Tfall_9c		—	3.0	—	3.0	—	3.0	—	3.0	ns		
MIIRXCLK, MIITXCLK <sup>2</sup>	Tper_9d	None	39.9	40.0	39.9	40.0	39.9	40.0	39.9	40.0	ns	100 Mbps	
	Thigh_9d, Tlow_9d		14.0	26.0	14.0	26.0	14.0	26.0	14.0	26.0	ns		
	Trise_9d, Tfall_9d		—	2.0	—	2.0	—	2.0	—	2.0	ns		
MIIRXD[3:0], MIIRXDV, MIIRXER	Tsu_9e	MIIRXCLK rising	10.0	—	10.0	—	10.0	—	10.0	—	ns		
	Thld_9e		10.0	—	10.0	—	10.0	—	10.0	—	ns		
MIITXD[3:0], MIITXENP, MIITXER	Tdo_9f	MIITXCLK rising	0.0	25.0	0.0	25.0	0.0	25.0	0.0	25.0	ns		
Ethernet — RMII Mode													
RMIREFCLK	Tper_9i	None	19.9	20.1	19.9	20.1	19.9	20.1	19.9	20.1	ns		See Figure 10.
	Thigh_9i, Tlow_9i		7.0	13.0	7.0	13.0	7.0	13.0	7.0	13.0	ns		
RMIITXEN, RMIITXD[1:0]	Tdo_9j	MIIRXCLK rising	2.0	—	2.0	—	2.0	—	2.0	—	ns		
RMIICRSDV, RMIIRXER, RMIIRXD[1:0]	Tsu_9k		5.5	14.5	5.5	14.5	5.5	14.5	5.5	14.5	ns		

Table 9 Ethernet AC Timing Characteristics

<sup>1</sup> The values for this symbol were determined by calculation, not by testing.

<sup>2</sup> The ethernet clock (MIIRXCLK and MIITXCLK) frequency must be equal to or less than 1/2 ICLK (MIIRXCLK and MIITXCLK  $\leq$  1/2(ICLK)).

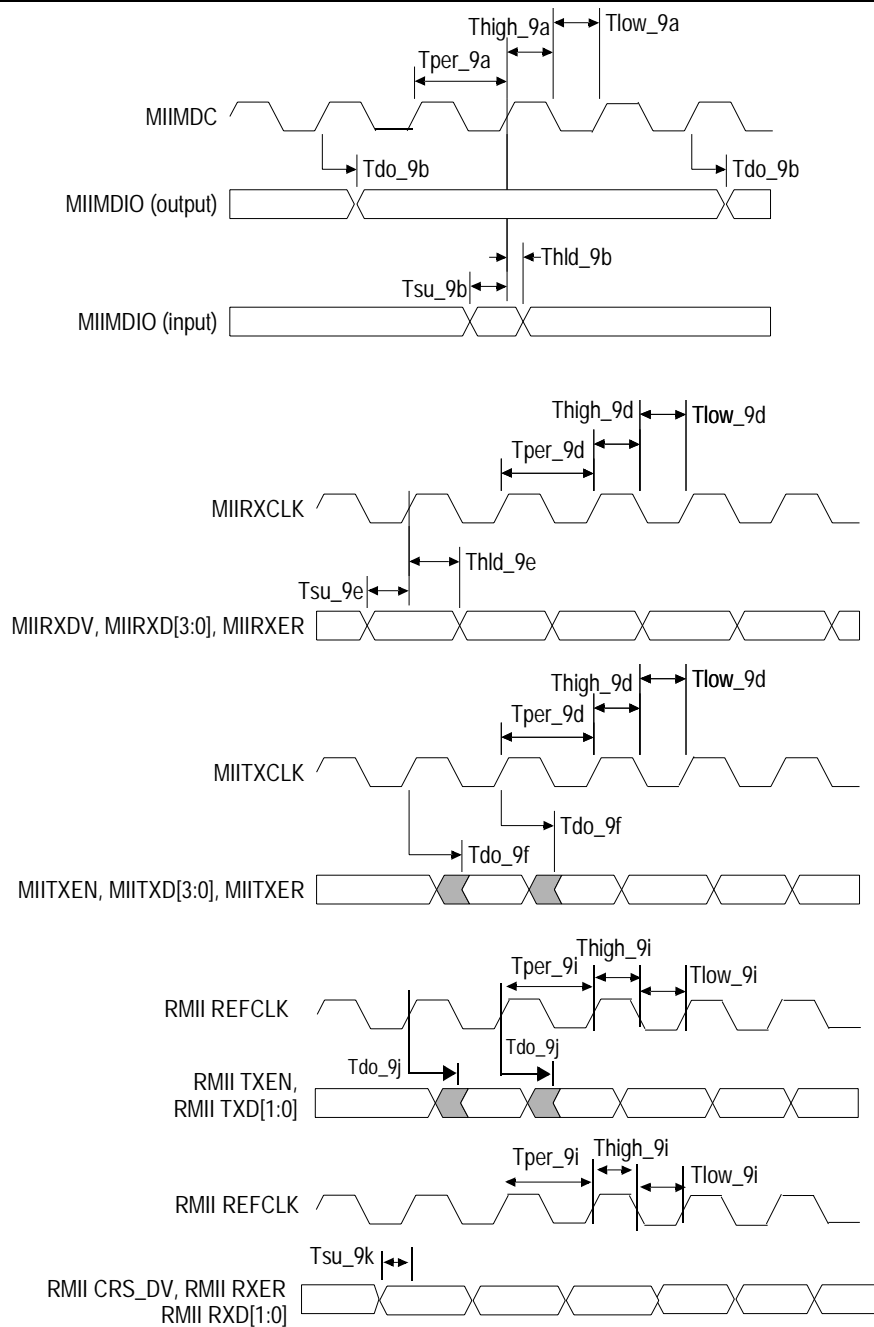


Figure 10 Ethernet AC Timing Waveform

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi- tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
PCI <sup>1</sup>													
PCICLK <sup>2</sup>	Tper_10a	none	15.0	30.0	15.0	30.0	15.0	30.0	15.0	30.0	ns	66 MHz PCI	See Figure 11.
	Thigh_10a, Tlow_10a		6.0	—	6.0	—	6.0	—	6.0	—	ns		
	Tslew_10a		1.5	4.0	1.5	4.0	1.5	4.0	1.5	4.0	V/ns		
PCIAD[31:0], PCIBEN[3:0], PCIDEVSELN, PCIFRA- MEN,PCIIR- DYN, PCIOCKN, PCIPAR, PCI- PERRN, PCIS- TOPN, PCITRDY	Tsu_10b	PCICLK rising	3.0	—	3.0	—	3.0	—	3.0	—	ns		
	Thld_10b		0	—	0	—	0	—	0	—	ns		
	Tdo_10b		2.0	6.0	2.0	6.0	2.0	6.0	2.0	6.0	ns		
	Tdz_10b <sup>3</sup>		—	14.0	—	14.0	—	14.0	—	14.0	ns		
	Tzd_10b <sup>3</sup>		2.0	—	2.0	—	2.0	—	2.0	—	ns		
PCIGNTN[3:0], PCIREQN[3:0]	Tsu_10c	PCICLK rising	5.0	—	5.0	—	5.0	—	5.0	—	ns		
	Thld_10c		0	—	0	—	0	—	0	—	ns		
	Tdo_10c		2.0	6.0	2.0	6.0	2.0	6.0	2.0	6.0	ns		
PCIRSTN (out- put) <sup>4</sup>	Tpw_10d <sup>3</sup>	None	4000 (CLK)	—	4000 (CLK)	—	4000 (CLK)	—	4000 (CLK)	—	ns		See Figures 15 and 16
PCIRSTN (input) <sup>4,5</sup>	Tpw_10e <sup>3</sup>	None	2(CLK)	—	2(CLK)	—	2(CLK)	—	2(CLK)	—	ns		
	Tdz_10e <sup>3</sup>	PCIRSTN falling	6(CLK)	—	6(CLK)	—	6(CLK)	—	6(CLK)	—	ns		
PCISERRN <sup>6</sup>	Tsu_10f	PCICLK rising	3.0	—	3.0	—	3.0	—	3.0	—	ns		See Figure 11
	Thld_10f		0	—	0	—	0	—	0	—	ns		
	Tdo_10f		2.0	6.0	2.0	6.0	2.0	6.0	2.0	6.0	ns		
PCIMUINTN <sup>6</sup>	Tdo_10g	PCICLK rising	4.7	11.1	4.7	11.1	4.7	11.1	4.7	11.1	ns		

Table 10 PCI AC Timing Characteristics

<sup>1</sup>. This PCI interface conforms to the PCI Local Bus Specification, Rev 2.2.

<sup>2</sup>. PCICLK must be equal to or less than two times ICLK ( $PCICLK \leq 2(ICLK)$ ) with a maximum PCICLK of 66 MHz.

<sup>3</sup>. The values for this symbol were determined by calculation, not by testing.

<sup>4</sup>. PCIRSTN is an output in host mode and an input in satellite mode.

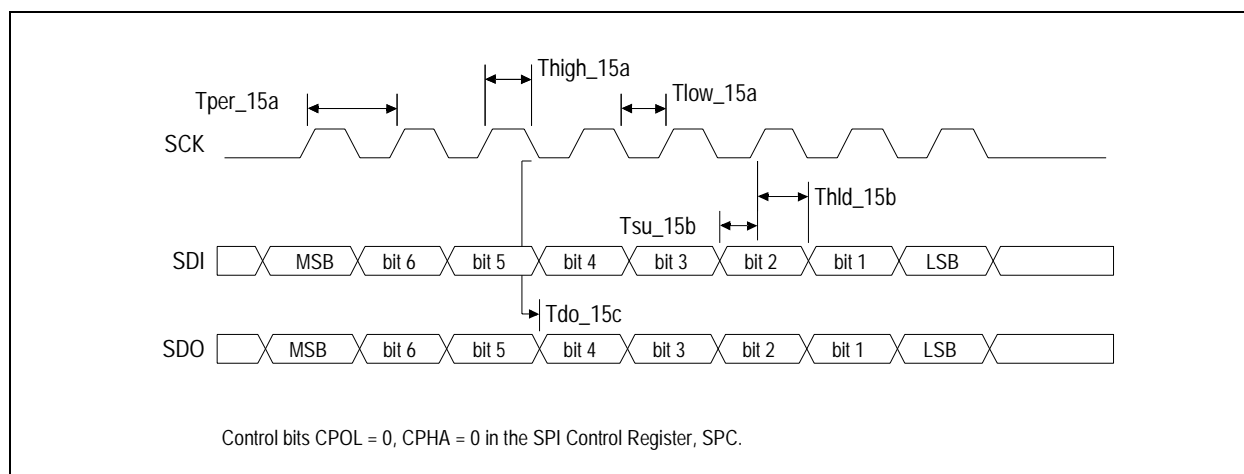
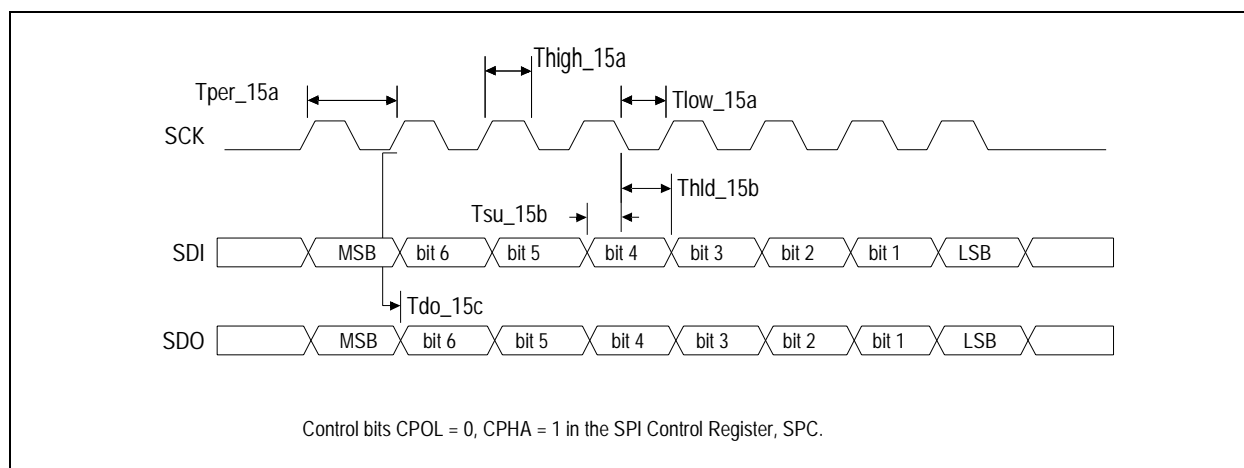
<sup>5</sup>. To meet the PCI delay specification from reset asserted to outputs floating, the PCI reset should be logically combined with the COLDSTN input, instead of input on PCIRSTN.

<sup>6</sup>. PCISERRN and PCIMUINTN use open collector I/O types.

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi-tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
SPI <sup>1</sup>													
SCK	Tper_15a	None	100	166667	100	166667	100	166667	100	166667	ns	SPI	See Figures 16, 17, and 18.
	Thigh_15a, Tlow_15a		40	83353	40	83353	40	83353	40	83353	ns	SPI	
SDI	Tsu_15b	SCK rising or falling	60	—	60	—	60	—	60	—	ns	SPI	See Figures 16, 17, and 18.
	Thld_15b		60	—	60	—	60	—	60	—	ns	SPI	
SDO	Tdo_15c	SCK rising or falling	0	60	0	60	0	60	0	60	ns	SPI	
SCK, SDI, SDO	Tpw_15e	None	2(ICLK)	—	2(ICLK)	—	2(ICLK)	—	2(ICLK)	—	ns	Bit I/O	

**Table 13 SPI AC Timing Characteristics**

<sup>1</sup> In SPI mode, the SCK period and sampling edge are programmable. In PCI mode, the SCK period is fixed and the sampling edge is rising.

**Figure 16 SPI AC Timing Waveform — Clock Polarity 0, Clock Phase 0****Figure 17 SPI AC Timing Waveform — Clock Polarity 0, Clock Phase 1**



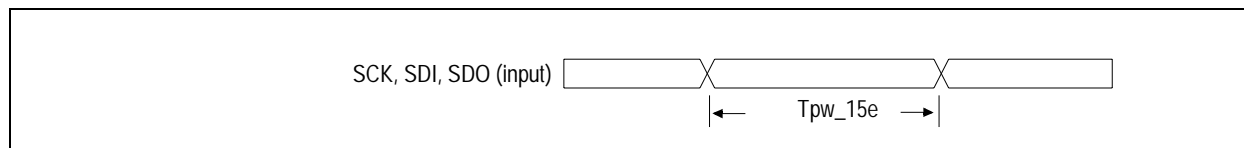


Figure 18 SPI AC Timing Waveform — Bit I/O Mode

Signal	Symbol	Reference Edge	266MHz		300MHz		350MHz		400MHz		Unit	Condi- tions	Timing Diagram Reference
			Min	Max	Min	Max	Min	Max	Min	Max			
EJTAG and JTAG													
JTAG_TCK	Tper_16a	none	25.0	50.0	25.0	50.0	25.0	50.0	25.0	50.0	ns		See Figure 19.
	Thigh_16a, Tlow_16a		10.0	25.0	10.0	25.0	10.0	25.0	10.0	25.0	ns		
JTAG_TMS <sup>1</sup> , JTAG_TDI	Tsu_16b	JTAG_TCK rising	2.4	—	2.4	—	2.4	—	2.4	—	ns		
	Thld_16b		1.0	—	1.0	—	1.0	—	1.0	—	ns		
JTAG_TDO	Tdo_16c	JTAG_TCK fall- ing	—	11.3	—	11.3	—	11.3	—	11.3	ns		
	Tdz_16c <sup>2</sup>		—	11.3	—	11.3	—	11.3	—	11.3	ns		
JTAG_TRST_N	Tpw_16d <sup>2</sup>	none	25.0	—	25.0	—	25.0	—	25.0	—	ns		
EJTAG_TMS <sup>1</sup>	Tsu_16e	JTAG_TCK rising	2.0	—	2.0	—	2.0	—	2.0	—	ns		
	Thld_6e		1.0	—	1.0	—	1.0	—	1.0	—	ns		

Table 14 JTAG AC Timing Characteristics

<sup>1</sup> The JTAG specification, IEEE 1149.1, recommends that both JTAG\_TMS and EJTAG\_TMS should be held at 1 while the signal applied at JTAG\_TRST\_N changes from 0 to 1. Otherwise, a race may occur if JTAG\_TRST\_N is deasserted (going from low to high) on a rising edge of JTAG\_TCK when either JTAG\_TMS or EJTAG\_TMS is low, because the TAP controller might go to either the Run-Test/Idle state or stay in the Test-Logic-Reset state.

<sup>2</sup> The values for this symbol were determined by calculation, not by testing.

## Recommended Operating Supply Voltages

Symbol	Parameter	Minimum	Typical	Maximum	Unit
$V_{SS}$	Common ground	0	0	0	V
$V_{SS}^{PLL}$	PLL ground				
$V_{CC}^{I/O}$	I/O supply except for SSTL_2 <sup>1</sup>	3.135	3.3	3.465	V
$V_{CC}^{SI/O} (DDR)$	I/O supply for SSTL_2 <sup>1</sup>	2.375	2.5	2.625	V
$V_{CC}^{PLL}$	PLL supply (digital)	1.1	1.2	1.3	V
$V_{CC}^{APLL}$	PLL supply (analog)	3.135	3.3	3.465	V
$V_{CC}^{Core}$	Internal logic supply	1.1	1.2	1.3	V
$DDRVREF$ <sup>2</sup>	SSTL_2 input reference voltage	$0.5(V_{CC}^{SI/O})$	$0.5(V_{CC}^{SI/O})$	$0.5(V_{CC}^{SI/O})$	V
$V_{TT}$ <sup>3</sup>	SSTL_2 termination voltage	$DDRVREF - 0.04$	$DDRVREF$	$DDRVREF + 0.04$	V

**Table 15 RC32434 Operating Voltages**

<sup>1</sup> SSTL\_2 I/Os are used to connect to DDR SDRAM.

<sup>2</sup> Peak-to-peak AC noise on DDRVREF may not exceed  $\pm 2\%$  DDRVREF (DC).

<sup>3</sup>  $V_{TT}$  of the SSTL\_2 transmitting device must track DDRVREF of the receiving device.

## Recommended Operating Temperatures

Grade	Temperature
Commercial	0°C to +70°C Ambient
Industrial	-40°C to +85°C Ambient

**Table 16 RC32434 Operating Temperatures**

## Capacitive Load Deration

Refer to the [79RC32434 IBIS Model](#) on the IDT web site ([www.idt.com](http://www.idt.com)).

## Power Consumption

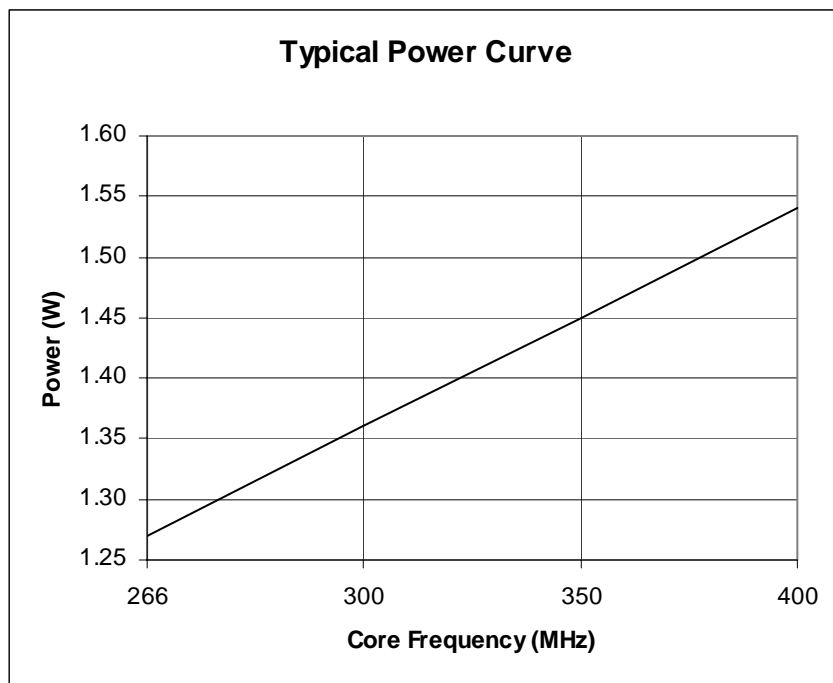
Parameter		266MHz		300MHz		350MHz		400MHz		Unit	Conditions
		Typ.	Max.	Typ.	Max.	Typ.	Max.	Typ.	Max.		
$I_{CC}$ I/O		215	270	220	275	225	280	230	285	mA	$C_L = 35$ pF $T_{ambient} = 25^{\circ}C$ Max. values use the maximum volt-ages listed in Table 15. Typical val-ues use the typical voltages listed in that table. Note: For additional information, see <a href="#">Power Considerations for IDT Processors</a> on the IDT web site <a href="http://www.idt.com">www.idt.com</a> .
$I_{CC}$ SI/O (DDR)		70	85	75	90	85	100	95	110	mA	
$I_{CC}$ Core, $I_{CC}$ PLL	Normal mode	325	510	350	550	400	610	450	670	mA	
	Standby mode <sup>1</sup>	220	—	240	—	260	—	280	—	mA	
Power Dissipation	Normal mode	1.27	1.82	1.36	1.90	1.45	2.02	1.54	2.15	W	
	Standby mode <sup>1</sup>	0.73	—	0.78	—	0.84	—	0.90	—	W	

**Table 17 RC32434 Power Consumption**

<sup>1</sup>. The RC32434 enter Standby mode by executing WAIT instructions. Minimal I/O switching is assumed. On-chip logic outside the CPU core continues to function.

## Power Curve

The following graph contains a power curve that shows power consumption at various core frequencies.



**Figure 22 RC32434 Typical Power Usage**

Signal Name	I/O Type	Location	Signal Category
DDRDATA[15]	I/O	H13	DDR Bus
DDRDM[0]	O	F15	
DDRDM[1]	O	G13	
DDRDQS[0]	I/O	J16	
DDRDQS[1]	I/O	G14	
DDRRASN	O	M13	
DDRVREF	I	J14	
DDRWEN	O	L14	
EJTAG_TMS	I	J4	JTAG / EJTAG
EXTBCV	I	D11	System
EXTCLK	O	C1	
GPIO[0]	I/O	H3	General Purpose Input/Output
GPIO[1]	I/O	H4	
GPIO[2]	I/O	J3	
GPIO[3]	I/O	J1	
GPIO[4]	I/O	A8	
GPIO[5]	I/O	B8	
GPIO[6]	I/O	C7	
GPIO[7]	I/O	A7	
GPIO[8]	I/O	L3	
GPIO[9]	I/O	M4	
GPIO[10]	I/O	P3	
GPIO[11]	I/O	M3	
GPIO[12]	I/O	M1	
GPIO[13]	I/O	T2	
JTAG_TCK	I	J2	JTAG / EJTAG
JTAG_TDI	I	A12	
JTAG_TDO	O	K1	
JTAG_TMS	I	C11	
JTAG_TRSTN	I	D12	

Table 24 RC32434 Alphabetical Signal List (Part 3 of 7)

Signal Name	I/O Type	Location	Signal Category
MADDR[0]	O	C15	Memory and Peripheral Bus
MADDR[1]	O	B16	
MADDR[2]	O	A16	
MADDR[3]	O	B15	
MADDR[4]	O	C14	
MADDR[5]	O	A15	
MADDR[6]	O	B14	
MADDR[7]	O	A14	
MADDR[8]	O	B13	
MADDR[9]	O	A13	
MADDR[10]	O	A5	
MADDR[11]	O	B5	
MADDR[12]	O	B10	
MADDR[13]	O	A10	
MADDR[14]	O	C10	
MADDR[15]	O	D10	
MADDR[16]	O	A9	
MADDR[17]	O	B9	
MADDR[18]	O	C9	
MADDR[19]	O	D9	
MADDR[20]	O	D8	
MADDR[21]	O	C8	
MDATA[0]	I/O	D7	
MDATA[1]	I/O	B6	
MDATA[2]	I/O	D6	
MDATA[3]	I/O	C5	
MDATA[4]	I/O	B7	
MDATA[5]	I/O	C6	
MDATA[6]	I/O	A6	
MDATA[7]	I/O	D5	

Table 24 RC32434 Alphabetical Signal List (Part 4 of 7)